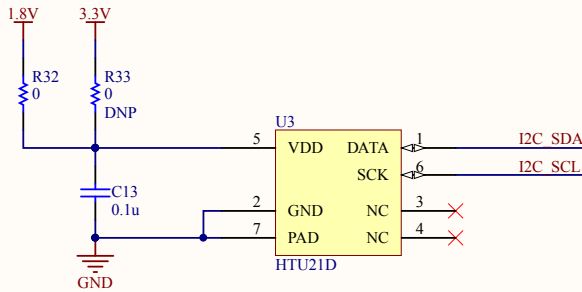


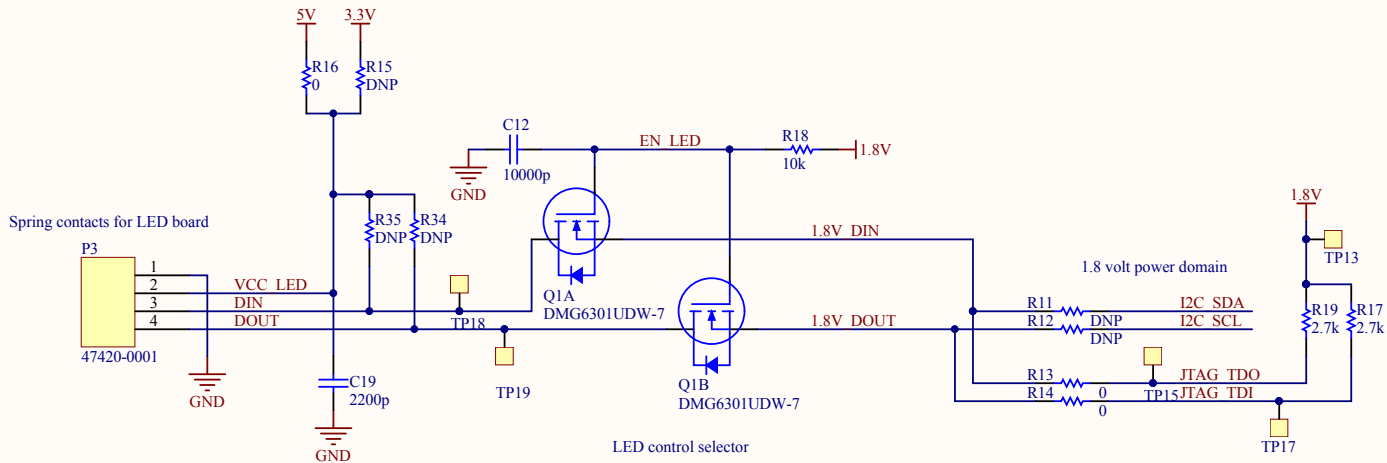


Supply needs to be 1.8V when I2C is pulled up to 1.8V. VIH for HTU21D is .7Vdd

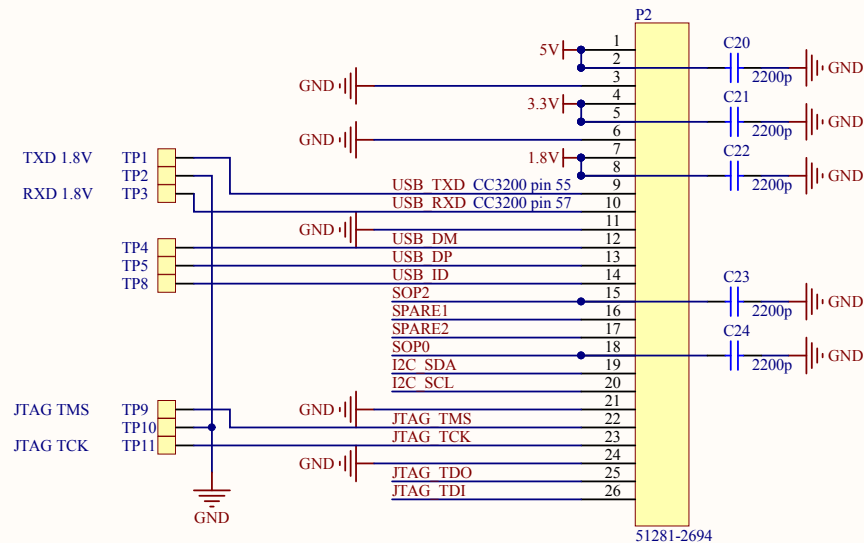
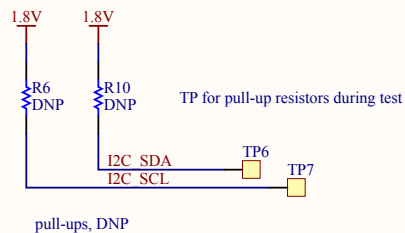


Hello

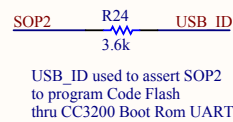
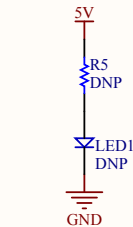
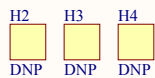
TITLE		REV
Temperature / Humidity		PVT
DATE	DRAWN BY	SHEET 2 OF 3
12/30/2014	D. Fusi	



connector to the middle board

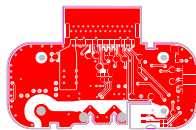


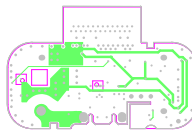
mounting holes. H1 has been replaced with a via

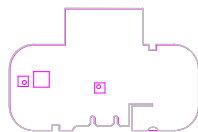


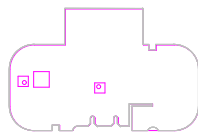
# Hello

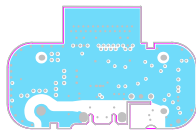
TITLE Morpheus_bottom		REV PVT
DATE 12/30/2014	DRAWN BY D. Fusi	SHEET 3 OF 3



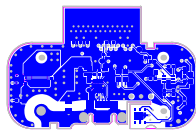


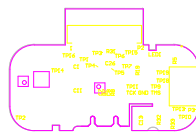


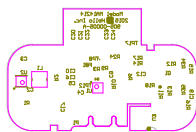


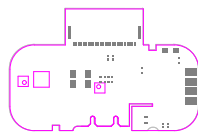


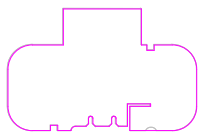


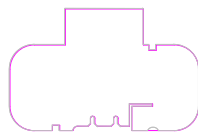








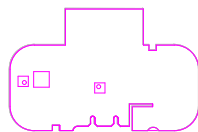










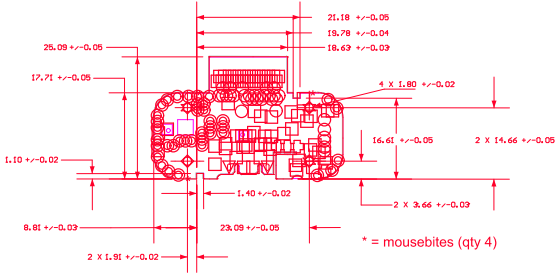



Fabrication / Assembly Notes

1. Material: Rigid FR-4, RoHS compliant; material should meet or exceed requirements of IPC 4101/126. ITEG IT-180A Pre-approved.  
2. Number of electrical layers: 4  
3. Trace / Space minimum: 5mil (all layers)  
4. Thickness: .97mm +/- 0.1mm (finished)  
5. Finish: ENIG plating on exposed copper  
6. Soldermask: per IPC-SM-840, color matte black registration within +/- 76um of circuit layer  
7. Silkscreen: use white silkscreen on top and bottom layers. Clip on pads.  
8. RoHS: parts shall be RoHS compliant as per European Union directive 2002/95/EC  
9. Board must be lead free process compatible and able to withstand minimum of 5 cycles at 250 degrees celsius  
10. All Test/QA/QC markings to be made on back side of PCB  
11. x mousebites shall be no larger than 0.05 mm  
12. All Dimensions are after plating/finishing  
13. All components must be placed within +/- 0.10mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.010mm	3.5	
4	Top Layer	Copper	0.036mm		
5	Dielectric1	FR-4	0.254mm	4.2	
6	GND	Copper	0.036mm		
7	Dielectric2	FR-4	0.330mm	4.2	
8	PdR	Copper	0.036mm		
9	Dielectric3	FR-4	0.254mm	4.2	
10	Bottom Layer	Copper	0.036mm		
11	Bottom Solder	Solder Resist	0.010mm	3.5	
12	Bottom Overlay				
13	Bottom Paste				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊙	1	1.800mm <70.87mil>	PTH	Round
▽	2	0.600mm <23.62mil>	PTH	Slot
⊙	3	1.800mm <70.87mil>	NPTH	Round
⊙	4	0.700mm <27.56mil>	PTH	Round
○	32	0.305mm <12.00mil>	PTH	Round
●	38	0.400mm <15.75mil>	PTH	Round
□	73	0.200mm <7.87mil>	PTH	Round
	153 Total			



METRIC		DRAWN	DATE	<div></div> <div>TITLE:</div> <div>Morpheus Bottom Board</div>	
DIMENSIONS ARE IN MILLIMETERS		DESIGNER	DATE		
TOLERANCES:		dfusi / rsb/ ben	01/12/2015		
0 > - < 2 0.10		PROPRIETARY AND CONFIDENTIAL THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF HELLO INC.  ANY REPRODUCTION IN PART OR AS A WHOLE, WITHOUT THE WRITTEN PERMISSION OF HELLO INC IS PROHIBITED.		SIZE	DWG. NO.
2 > - < 10 0.10				B	201-00005-A
10 > - < 50 0.10					
50 > - < 100 0.15					
100 > - < 200 0.20					
200 > - 0.20					
ANGLES 1.00				SCALE: 2:1	WEIGHT:
				SHEET 1 OF 1	

